

ABSTRACT

[00396] A brittle substrate cutting system according to the present invention includes a scribing apparatus including a scribing line forming means for forming a scribing line on a first surface of a brittle substrate; and a breaking apparatus for breaking the brittle substrate along the scribing line, wherein the breaking apparatus includes a first pressing controlling means for moving a pressing force upon a second surface of the brittle substrate opposing the first surface of the brittle substrate along the scribing line while the first surface of the brittle substrate is held.